



Material Composition Declaration

EPC2934C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/6/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	15.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	13.8376	89.3005	92.9260	893005
	Silicon oxide	7631-86-9	0.0692	0.4466		4466
	Silicon nitride	12033-89-5	0.0246	0.1587		1587
	Gallium nitride	25617-97-4	0.1226	0.7913		7913
	Aluminum	7429-90-5	0.1439	0.9288		9288
	Aluminum nitride	24304-00-5	0.0274	0.1770		1770
	Titanium	7440-32-6	0.0037	0.0237		237
	Titanium nitride	25583-20-4	0.0190	0.1225		1225
	Copper	7440-50-8	0.0024	0.0155		155
	Tungsten	7440-33-7	0.0025	0.0160		160
	Polyimide		0.1465	0.9455	9455	
Under Bump Metal	Titanium	7440-32-6	0.0017	0.0109	0.0545	109
	Copper	7440-50-8	0.0067	0.0435		435
Solder Bump	Copper	7440-50-8	0.0843	0.5442	7.0195	5442
	Nickel	7440-02-0	0.0503	0.3246		3246
	Lead	7439-92-1	0.9054	5.8432		58432
	Tin	7440-31-5	0.0477	0.3075		3075
Sum in total:			15.4956	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.